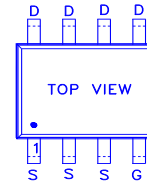
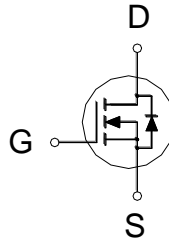


PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
30V	14.3m Ω	8.4A



G: GATE
D: DRAIN
S: SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_A = 25^\circ\text{C}$	I_D	8.4	A
	$T_A = 70^\circ\text{C}$		6.7	
Pulsed Drain Current ¹		I_{DM}	33	
Avalanche Current		I_{AS}	14.5	
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	10.5	mJ
Power Dissipation	$T_A = 25^\circ\text{C}$	P_D	1.9	W
	$T_A = 70^\circ\text{C}$		1.2	
Junction & Storage Temperature Range		T_J, T_{stg}	-55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient	$R_{\theta JA}$		65	$^\circ\text{C} / \text{W}$
Junction-to-Case	$R_{\theta JC}$		25	

¹Pulse width limited by maximum junction temperature.

²The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

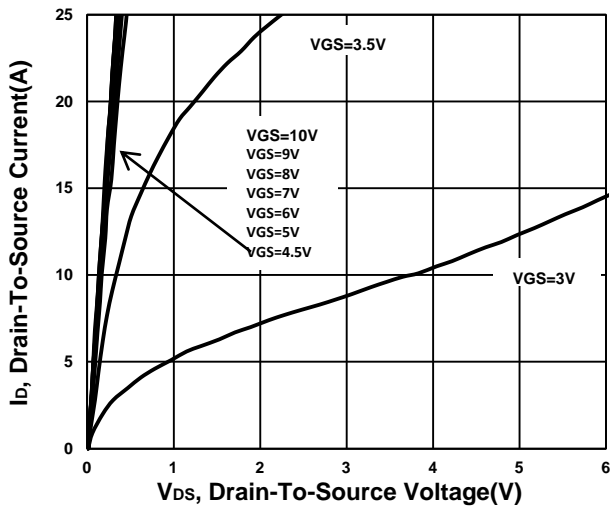
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.3	1.8	2.3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 24\text{V}, V_{GS} = 0\text{V}$			1	μA
		$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}, T_J = 55^\circ\text{C}$			10	
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 4.5\text{V}, I_D = 6.8\text{A}$		15	18.4	m Ω
		$V_{GS} = 10\text{V}, I_D = 8\text{A}$		11	14.3	

Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 8A$		30		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 15V, f = 1MHz$		419		pF
Output Capacitance	C_{oss}			83		
Reverse Transfer Capacitance	C_{rss}			51		
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$		3.2		Ω
Total Gate Charge ²	$Q_{g(VGS=10V)}$	$V_{DS} = 15V, I_D = 8A$		9		nC
	$Q_{g(VGS=4.5V)}$			5		
Gate-Source Charge ²	Q_{gs}			1.3		
Gate-Drain Charge ²	Q_{gd}			2.7		
Turn-On Delay Time ²	$t_{d(on)}$		$V_{DS} = 15V, I_D \cong 8A, V_{GS} = 10V, R_{GEN} = 6\Omega$		17	
Rise Time ²	t_r			16		
Turn-Off Delay Time ²	$t_{d(off)}$			33		
Fall Time ²	t_f			18		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_J = 25 ° C)						
Continuous Current	I_S			1.6		A
Forward Voltage ¹	V_{SD}	$I_F = 8A, V_{GS} = 0V$		1.1		V
Diode Reverse Recovery Time	t_{rr}	$I_F = 8A, di/dt = 100A/\mu s$		11		nS
Diode Reverse Recovery Charge	Q_{rr}			2.2		nC

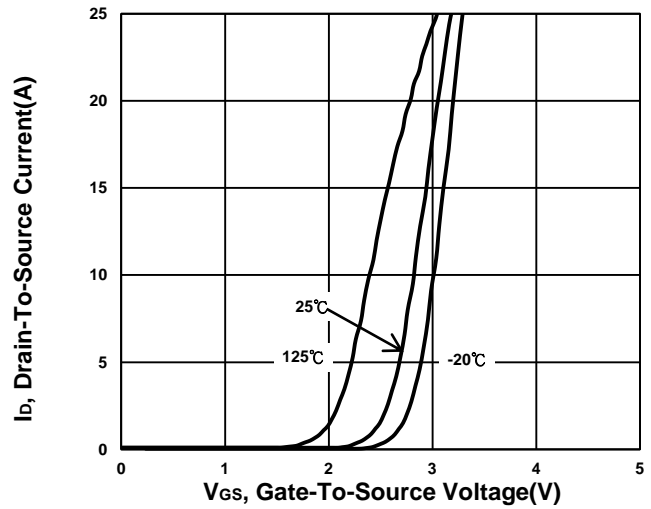
¹Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

²Independent of operating temperature.

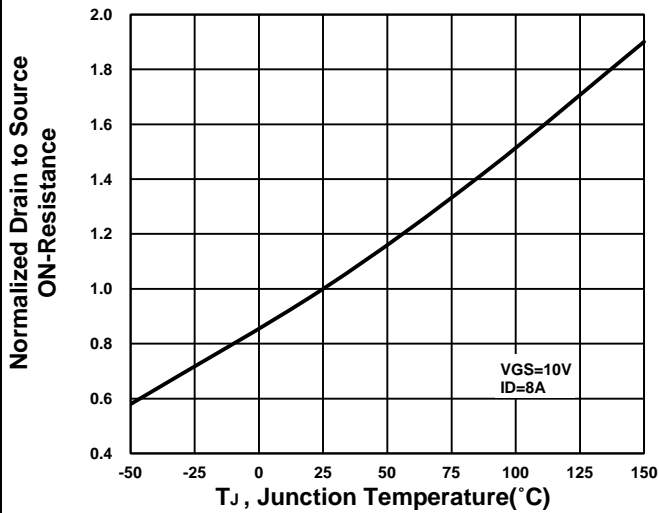
Output Characteristics



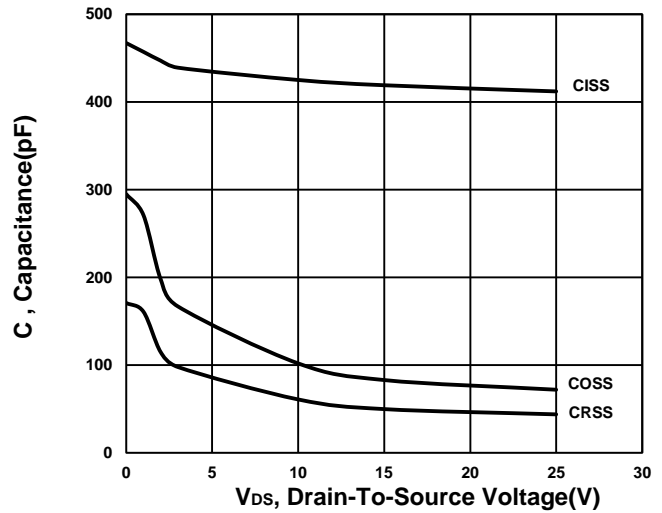
Transfer Characteristics



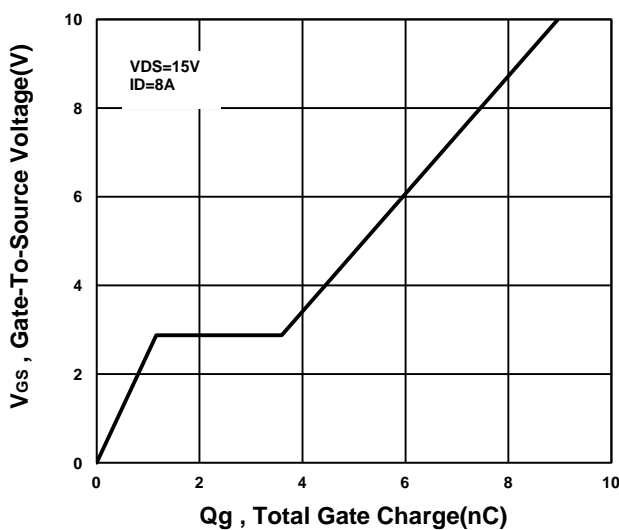
On-Resistance VS Temperature



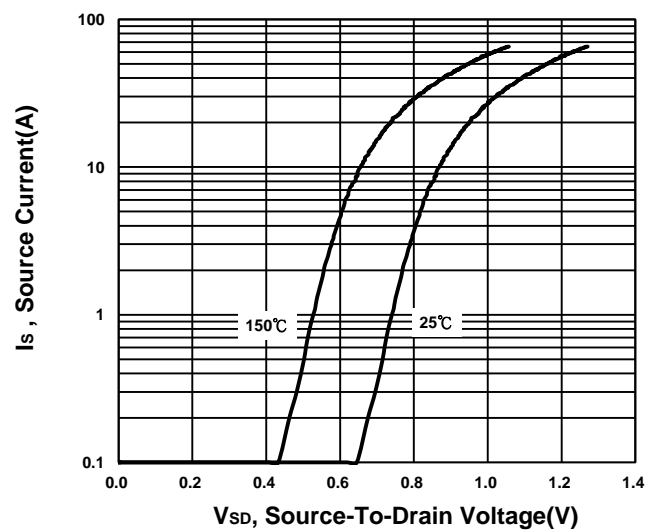
Capacitance Characteristic



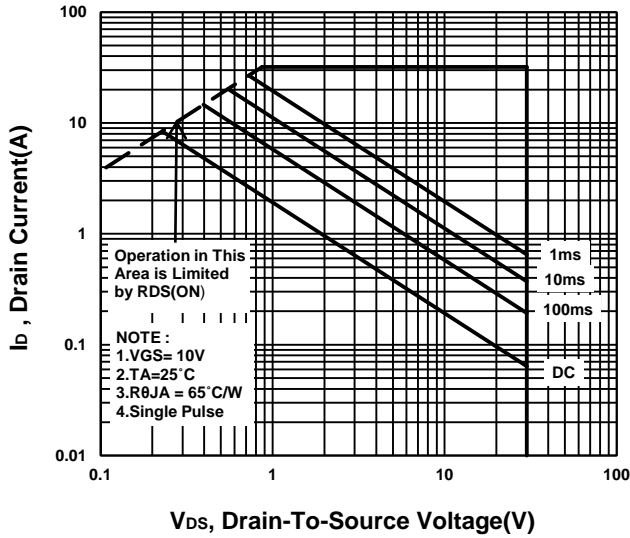
Gate charge Characteristics



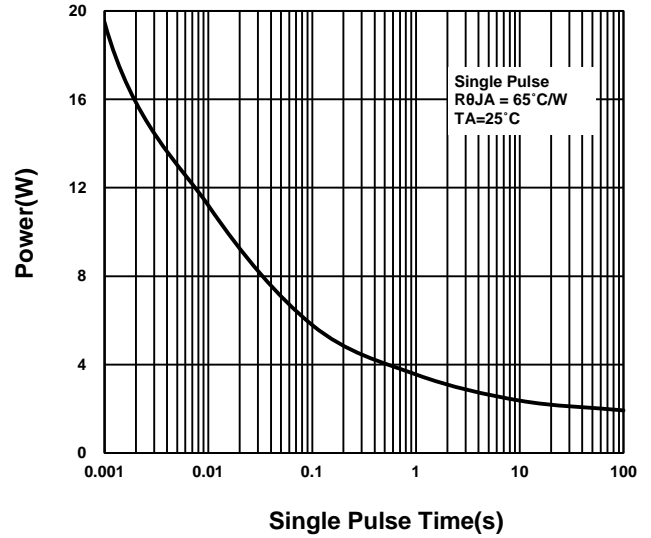
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

